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U.S. PATENT DOCUMENTS

Exam Init	Ref	Document Number	Issue Date	Name	Class	Sub Class
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II		6,080,931	6/27/2000	Park, et al.		

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II		2001-028422	1/30/2001	Japan	Koyo and Yuji
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II		English language of Abstract for Japanese Patent Publication No. 08-070079, published 3/12/1996.
II		English language of Abstract for Japanese Patent Publication No. 05-283608, published 10/29/1993.
II		English language of Abstract for Japanese Patent Publication No. 2001-028422, published 1/30/2001.
II		English language of Abstract for Japanese Patent Publication No. 2001-185651, published 7/6/2001.
II		English language of Abstract for Japanese Patent Publication No. 08-279591, published 10/22/1996.

Examiner:

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